

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

~~I CLAIM~~ What is claimed is:

1-24. (Canceled).

~~24~~25. (Amended) An encapsulation method for leadless semiconductor packages, the method comprising:

attaching a plurality of dice to die pads in a plurality of cavities of a lead frame, the cavities arranged in a matrix of columns and rows;

electrically connecting the dice to a plurality of conducting portions of the leadframe; ~~and~~
causing a molding material to flow into a first cavity;

causing said molding material to flow from said first cavity into a second cavity adjacent to and in the same column as said first cavity; and

causing said molding material to flow from said first cavity into a third cavity adjacent to and in the same row as said first cavity.

~~25~~26. (Amended) The encapsulation method of Claim ~~24~~25, further comprising causing said molding material to flow from said first cavity into a fourth cavity adjacent to and in the same row as said first cavity.

~~26~~27. (Amended) The encapsulation method of Claim ~~24~~25, further comprising:
causing said molding material to flow from said second cavity into a fourth cavity
adjacent to and in the same column as said first cavity; and
causing said molding material to flow from said second cavity into a fifth cavity adjacent
to and in the same row as said second cavity.